



Product Specification For TFT Module

Model Name	XEG0039FHD01A1-C
Customer	
Note	

☒ Preliminary Specification

☐ Final Specification

☐ CUSTOMER'S APPROVAL
BY:
DATE:
Comment

PRESENTED BY

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1. General Description

XEG0039FHD01A1-C is a 0.39 inch (1 cm) diagonal, FHD resolution(1920 x1080), active matrix color OLED (Organic Light Emitting Display) panel module based on single crystal silicon backplane . The pixel circuits and driving IC are integrated on the silicon backplane to get the compact size and very low power consumption.

(Potential applications: Virtual Reality application (AR/VR) , Head mounted displays, Near-Eye Displays etc.)

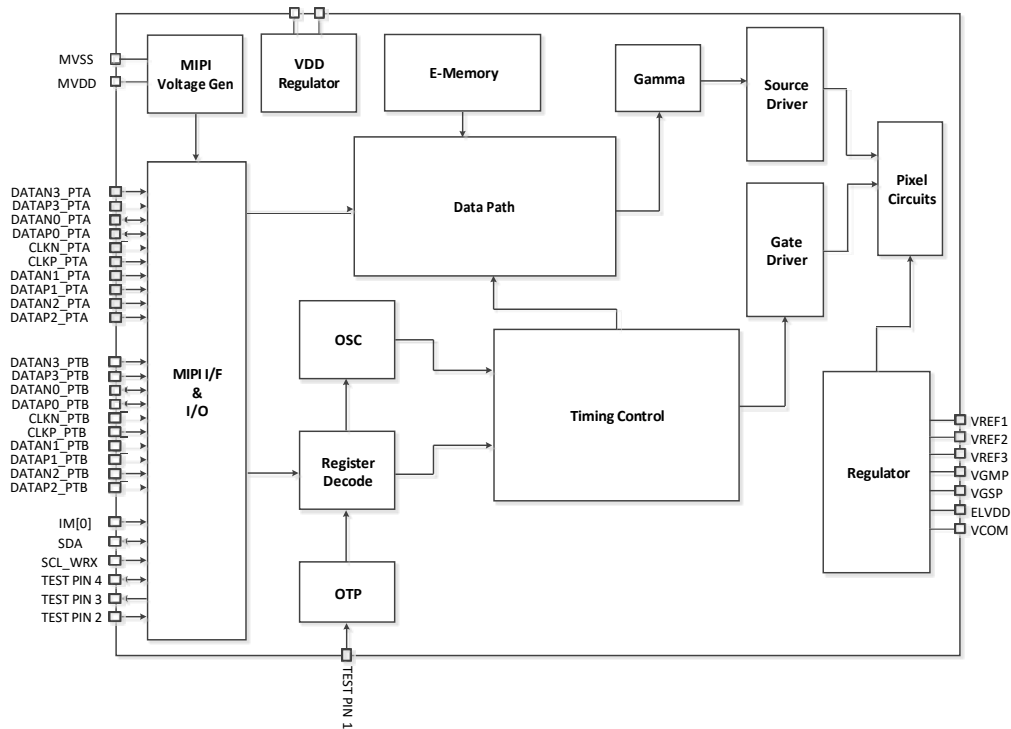
2. Features

- Small-size, high resolution 0.39 FHD Display PPI=5644
- AP Operated Resolution (8*M, M=40~240) x RGB x (8*N, N=30~135)
- Full color mode, 16.7M colors
- Fast response
- Thin and light in weight
- Color enhancement, Sharpness enhancement
- High contrast mode
- High fluency mode
- Power-saving (PS) mode
- Scan direction selection, up or down
- Interface, Support MIPI only or MIPI+I²C

3. Module Structure

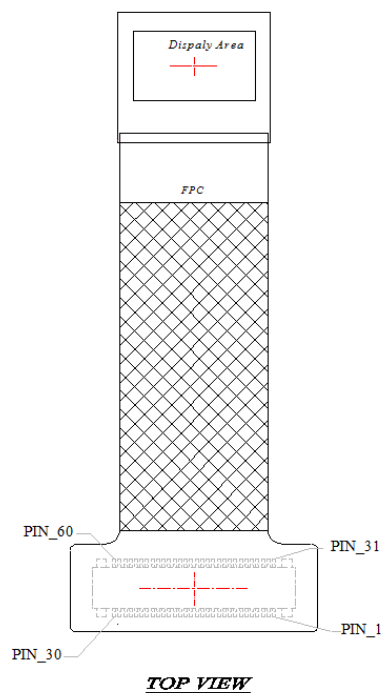
- Active matrix color OLED display with on-chip driver based on single crystal silicon transistors

4. Block Diagram



5. Pin Description

5.1 Pin Assignment



- FPC module

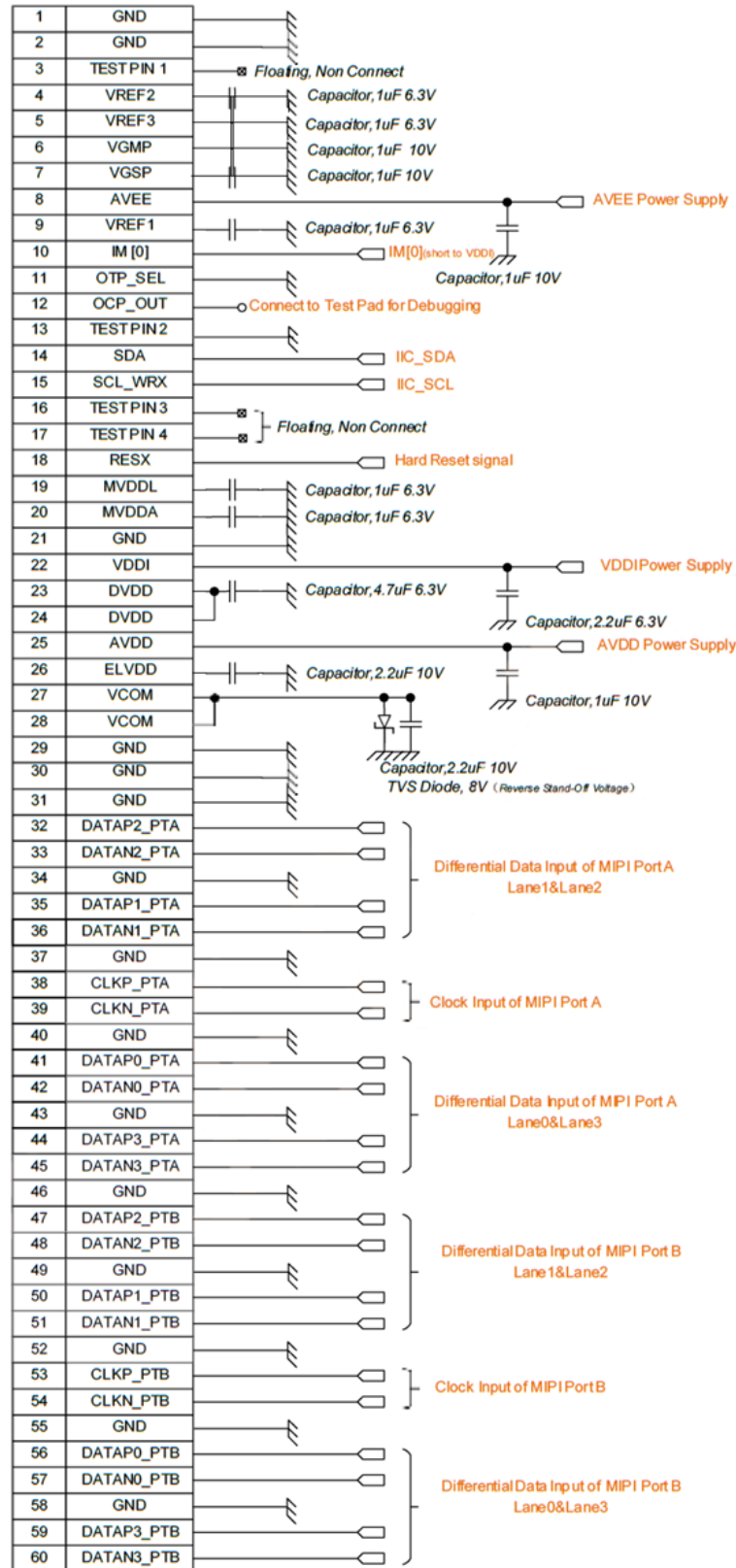
5.2 Pin description of FPC Module

PIN No. (FPC Side)	Symbol	Type	Description									
1	GND	Power Supply	Circuit ground									
2	GND	Power Supply	Circuit ground									
3	TEST PIN 1	Input	TEST pin （no connect, Floating ）									
4	VREF2	Output	VREF voltage, Connect a capacitor for stabilization									
5	VREF3	Output	VREF voltage, Connect a capacitor for stabilization									
6	VGMP	Output	Gamma top voltage, Connect a capacitor for stabilization									
7	VGSP	Output	Gamma bottom voltage, Connect a capacitor for stabilization									
8	AVEE	Power Supply	Power supply for OLED cell, Connect a capacitor for stabilization									
9	VREF1	Output	VREF voltage, Connect a capacitor for stabilization									
10	IM [0]	Input	Use to select the Interface type.									
			<table><tr><th>IM [0]</th><th>Command Execute</th><th>Image Write</th></tr><tr><td>0</td><td>MIPI</td><td>MIPI</td></tr><tr><td>1</td><td>I2C/MIPI</td><td>MIPI</td></tr></table>	IM [0]	Command Execute	Image Write	0	MIPI	MIPI	1	I2C/MIPI	MIPI
			IM [0]	Command Execute	Image Write							
			0	MIPI	MIPI							
1	I2C/MIPI	MIPI										
Note: Recommend to short to VDDI												
11	OTP_SEL	Input	MTP type selection. OTP_SEL, connect to GND : use internal OTP									
12	OCP_OUT	Output	Over current protect flag									
13	TEST PIN 2	Input	TEST pin, connect to GND									
14	SDA	Input/ Output	Bi-direction data PIN in I2C I/F If this pin is not used, please connect to VDDI									
15	SCL_WRX	Input	Synchronous clock signal in I2C I/F. If this pin is not used, please connect to VDDI									
16	TEST PIN 3	Output	TEST pin, （no connect, Floating ）									
17	TEST PIN 4	Input/ Output	TEST pin, （no connect, Floating ）									
18	RESX	Input	This signal will reset the device and must be applied to properly initialize the chip, Signal is active low									
19	MVDDL	Output	Internal system Power, Connect a capacitor for stabilization									
20	MVDDA	Output	Internal system Power, Connect a capacitor for stabilization									
21	GND	Power Supply	Circuit ground									
22	VDDI	Power Supply	External power supply （1.8V for digital system power）									
23	DVDD	Output	Internal system Power, Connect a capacitor for stabilization									
24	DVDD	Output	Internal system Power, Connect a capacitor for stabilization									
25	AVDD	Power Supply	Power supply for OLED cell, Connect a capacitor for stabilization									
26	ELVDD	Output	Power supply for OLED cell, Connect a capacitor for stabilization									
27	VCOM	Output	Power supply for OLED cell, Connect a capacitor for stabilization									
28	VCOM	Output	Power supply for OLED cell, Connect a capacitor for stabilization									
29	GND	Power Supply	Circuit ground									

30	GND	Power Supply	Circuit ground
31	GND	Input	Circuit ground for MIPI
32	DATAP2_PTA	Input	Differential small amplitude signal of MIPI data input
33	DATAN2_PTA	Input	Differential small amplitude signal of MIPI data input
34	GND	Input	Circuit ground for MIPI
35	DATAP1_PTA	Input	Differential small amplitude signal of MIPI data input
36	DATAN1_PTA	Input	Differential small amplitude signal of MIPI data input
37	GND	Input	Circuit ground for MIPI
38	CLKP_PTA	Input	MIPI CLK
39	CLKN_PTA	Input	MIPI CLK
40	GND	Input	Circuit ground for MIPI
41	DATAP0_PTA	Input/ Output	Differential small amplitude signal of MIPI data input
42	DATAN0_PTA	Input/ Output	Differential small amplitude signal of MIPI data input
43	GND	Input	Circuit ground for MIPI
44	DATAP3_PTA	Input	Differential small amplitude signal of MIPI data input
45	DATAN3_PTA	Input	Differential small amplitude signal of MIPI data input
46	GND	Input	Circuit ground for MIPI
47	DATAP2_PTB	Input	Differential small amplitude signal of MIPI data input
48	DATAN2_PTB	Input	Differential small amplitude signal of MIPI data input
49	GND	Input	Circuit ground for MIPI
50	DATAP1_PTB	Input	Differential small amplitude signal of MIPI data input
51	DATAN1_PTB	Input	Differential small amplitude signal of MIPI data input
52	GND	Input	Circuit ground for MIPI
53	CLKP_PTB	Input	MIPI CLK
54	CLKN_PTB	Input	MIPI CLK
55	GND	Input	Circuit ground for MIPI
56	DATAP0_PTB	Input/ Output	Differential small amplitude signal of MIPI data input
57	DATAN0_PTB	Input/ Output	Differential small amplitude signal of MIPI data input
58	GND	Input	Circuit ground for MIPI
59	DATAP3_PTB	Input	Differential small amplitude signal of MIPI data input
60	DATAN3_PTB	Input	Differential small amplitude signal of MIPI data input

5.3 Peripheral Circuit

FPC Module



Mount the capacitor for each power supply to ensure that the panel display normally.

Notes:

No.	Signal Name	Typical Value	Maximum Rated Voltage	Note
1	VDDI	Cap, 2.2uF	6.3V	
2	AVDD	Cap, 1.0uF	10V	
3	ELVDD	Cap, 2.2uF	10V	
4	AVEE	Cap, 1.0uF	10V	
5	DVDD	Cap, 4.7uF	6.3V	
6	MVDDA	Cap, 1uF	6.3V	
7	MVDDL	Cap, 1uF	6.3V	
8	VGMP	Cap, 1uF	10V	
9	VGSP	Cap, 1uF	10V	
10	VREF1	Cap, 1uF	6.3V	
11	VREF2	Cap, 1uF	6.3V	
12	VREF3	Cap, 1uF	6.3V	
13	VCOM	Cap, 2.2uF TVS	10V	

- (1) There are totally 13 capacitors and 1 TVS diode.
- (2) The TVS diode is placed between VCOM and ground, and the anode connect to Vcom, the cathode connect to GND.

5.4 Interface

0.39" Micro OLED supports MIPI interface and inter-integrated circuit interface(I2C). 1 port MIPI or 2 port MIPI is selected by register, and I2C is selected by IM0, the detail interface selection by IM0 pin and register of PORT1_2_SEL shows in below table.

IM0	PORT1_2_SEL	Command Execute	Image Write
0	0	MIPI	MIPI 1port
0	1	MIPI	MIPI 2 port
1	0	I2C	MIPI 1port
1	1	I2C	MIPI 2 port

5.4.1 I2C Interface

The I2C-bus is for bi-directional, two-line communication between different ICs or modules. The two lines are the Serial Data Line (I2C_SDA) and Serial Clock Line(I2C_SCL). Both lines must be

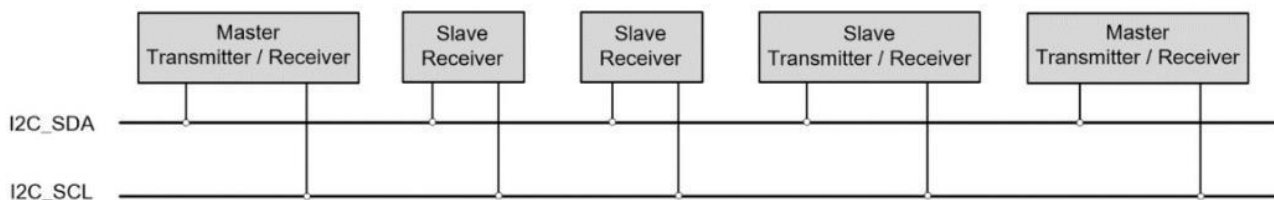
connected to a positive power supply via pull-up resistors. Data transfer can be initiated only when the bus is not busy. The acknowledge takes place after every byte. The acknowledge bit allows the receiver to signal the transmitter that the byte was successfully received and another byte may be sent. The master generates all clock pulses, including the acknowledge ninth clockpulse.

5.4.1.1 I2C-Bus Protocol

Before any data is transmitted on the I2C-bus, the device which should response is addressed first. There are several slave addresses can be selected by MCU. The slave addressing is always

Definition

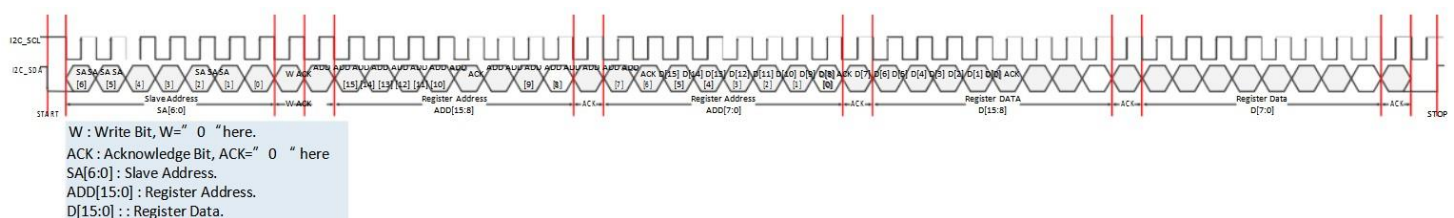
- Transmitter: The device which sends the data to the bus.
- Receiver: The device which receives the data from the bus.
- Master: The device which initiates a transfer, generates clock signals and terminates a transfer.
- Slave: The device addressed by a master.
- Multi-master: More than one master can attempt to control the bus at the same time without corrupting the message.
- Arbitration: Procedure to ensure that. If more than one master simultaneously tries to control the bus, only one is allowed to do so and the message is not corrupted.
- Synchronization: Procedure to synchronize the clock signals of two or more devices.



5.4.1.2 Write Sequence

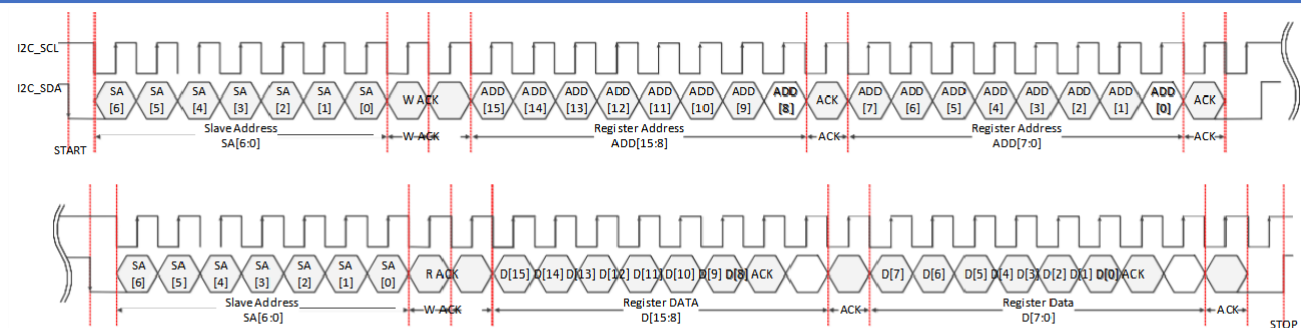
0.39" Micro OLED supports register write sequence via I2C-bus transfer. The register writing supports single register write mode. The detailed transfer sequences are illustrated and described as below.

- (1) Data transfer for register writing should follow the format shown as below.
- (2) After the START condition, a slave address is sent. R/Wbit is setting to "0" for Write.
- (3) The slave issues an ACK to the master.
- (4) 8-bits register address transfer first then transfer the register data parameter.
- (5) A data transfer is always terminated by a STOP condition
- (6) The chip SA[6:0]=100_1100.



5.4.1.3 Read Sequence

0.39" Micro OLED supports register read sequence via I2C-bus transfer. The register reading supports singleregister read mode. The register data reading transfer are shown as below.



W : Write Bit, W=" 0 " here.

R : Read Bit, R=" 1 " here.

ACK : Acknowledge Bit, ACK=" 0 " here

SA[6:0] : Slave Address.

ADD[15:0] : Read Register Address.

D[15:0] : Read Register Return Data.

5.4.2 MIPI Interface

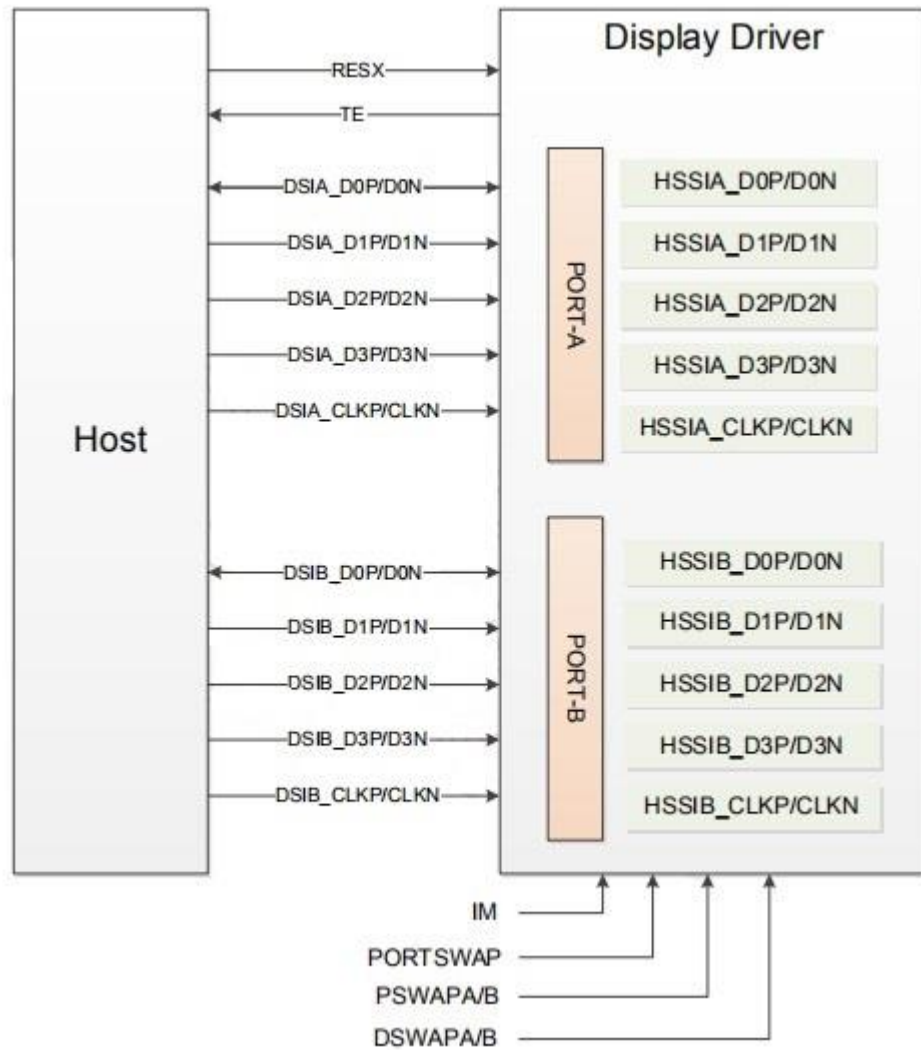
Display serial interface(DSI) specifies the interface between a host processor and a peripheral such as a display module. It builds on existing MIPI Alliance specification by adoption pixel formats and command set. The detail Lane configuration for DPHY is listed below.

There are one Clock Lane and 1~4 Data Lane. The configuration for DPHY between host and 0.39" Micro OLED shows as the table below.

Lane Pair	Available Operation Mode	
Clock Lane	Unidirectional Lane	Forward High-Speed Clock Escape Mode (ULPS only)
Data Lane 0	Bi-directional Lane	Forward High-Speed Data Bi-directional Escape Mode Bi-directional LPDT
Data Lane 1	Unidirectional Lane	Forward High-Speed Data No LPDT Escape Mode (ULPM only)
Data Lane 2	Unidirectional Lane	Forward High-Speed Data No LPDT Escape Mode (ULPM only)
Data Lane 3	Unidirectional Lane	Forward High-Speed Data No LPDT Escape Mode (ULPM only)

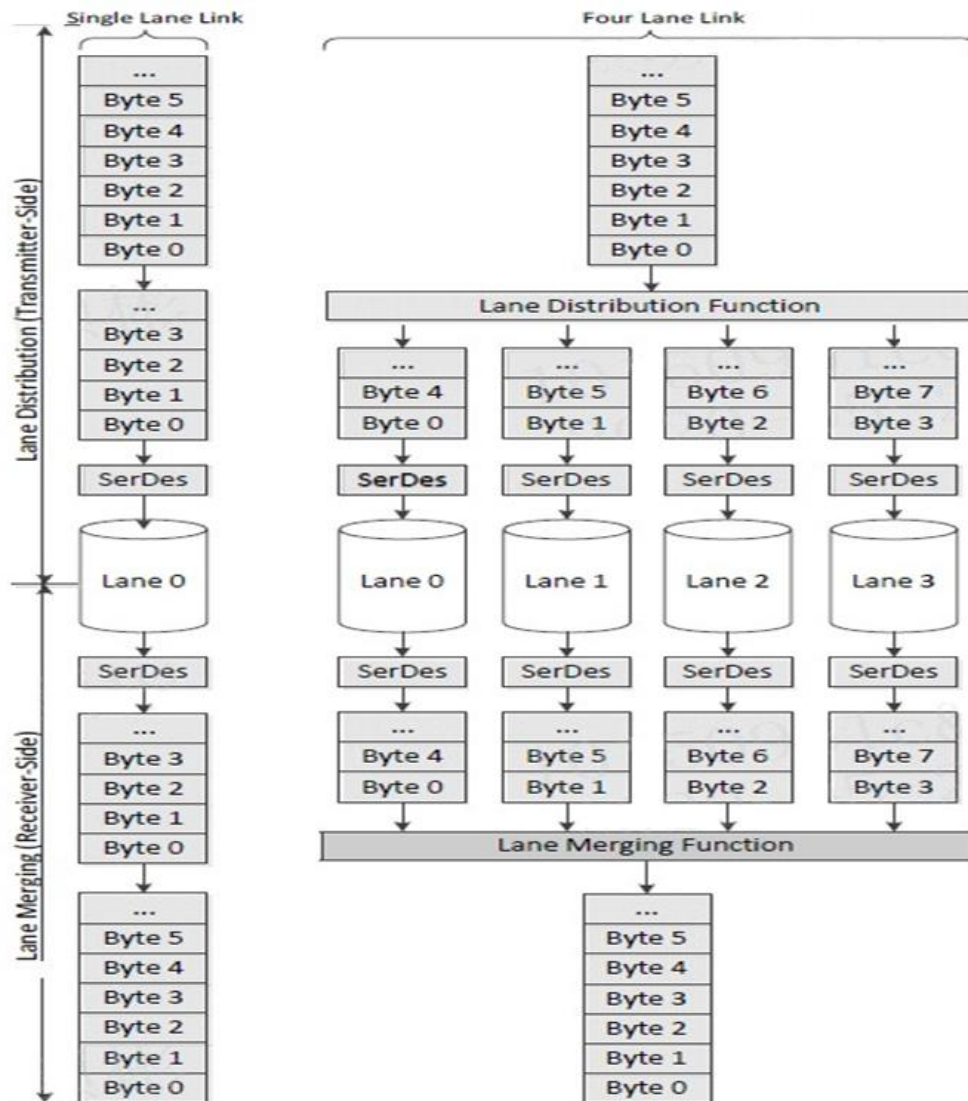
5.4.2.1 DSI System Configuration

0.39" MICRO OLED supports MIPI 1 port with 2, 3 or 4 lane configurations for DPHY. The system configuration is shown as the figure below. There are HW pin (IM) and registers (Lane_num_cfg, PSWAP, DSWAP) which can set the interface and lane related configuration



5.4.2.2 Multi-Lane Distribution and Merging

DSI is a lane-scalable interface. Multi-lane implementations shall use a single common clock signal, shared by all data lane. In the transmitter, there will be a layer to distribute a sequence of packet bytes across N Lanes. And in the receiver, there will be a layer to merge this sequence of packet byte back to correct order. The data processing flow is shown as the figure below for DPHY one-lane/four-lane condition.

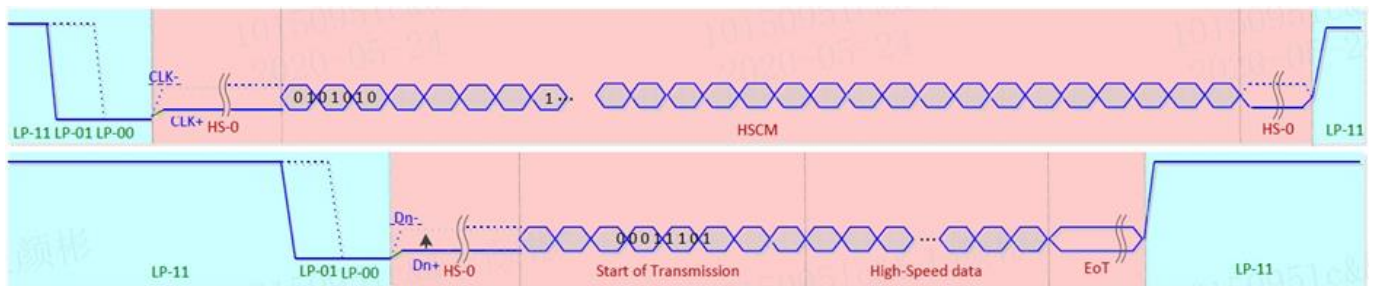


5.4.2.5 Low Power Data Transmission

If the Escape mode Entry procedure is followed up by Entry Command for Low Power Data Transmission (LPDT).

Data can be communicated by the protocol at low speed. The LPDT waveform is as follows and the figure below.

1. Escape mode Entry Sequence
2. Escape Entry Command(87h) for LPDT
3. LP data for LPDT
4. Mark-1 to leave Escape mode



The MCU can force data lane in Ultra-Low-Power State(ULPS) by Escape Mode with ULPS Entry Command. The sequence to force data lane in ULPS is as follows and the figure below.

1. Escape mode Entry Sequence
2. Escape Entry Command(78h) for ULPS
3. Mark-1 to leave Escape mode

5.4.2.6 High-Speed Data Transmission (HSDT)

For High-Speed Data Transmission in DPHY, Clock lane have to enter High-Speed Clock Mode (HSCM) before Data lanes enter High-Speed Data Transmission. And the Data lanes have to leave High-Speed Data Transmission after Clock lanes already left HSCM. The High-Speed Data Transmission sequence for DPHY is as the figure below.

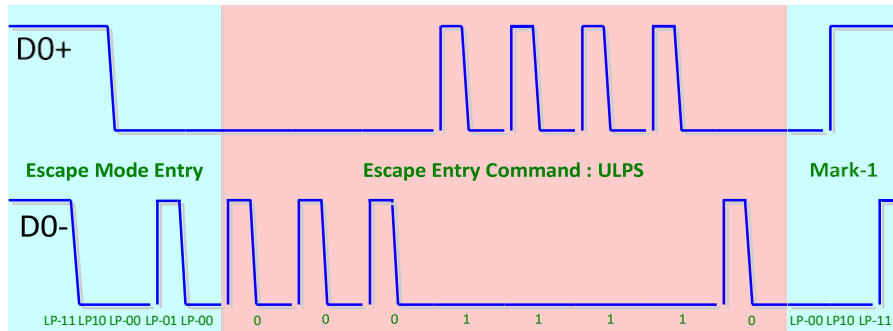
■ Data Lane

1. HS request sequence: LP-11 → LP-01 → LP-00
2. Keep HS-0 for certain time
3. Start of Transmission sequence (B8h)
4. HS data for HSDT
5. End of Transmission sequence (HS-0 if last data bit is HS-1, HS-1 if last data bit is HS-0)
6. Back to LP-11 to leave HSDT

■ Clock Lane

1. HS request sequence: LP-11 → LP-01 → LP-00
2. Keep HS-0 for certain time
3. High speed clock mode
4. Keep HS-0 for certain time

5. Back to LP-11 to leave HSCM

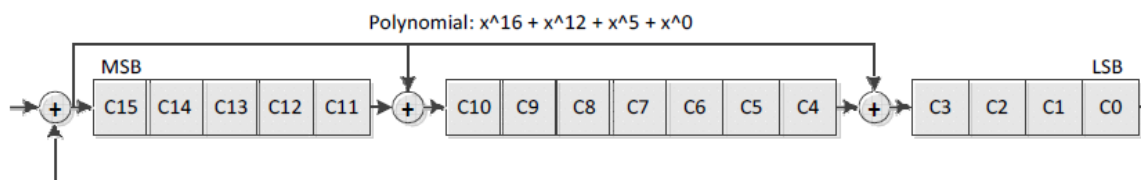


5.4.2.7 Interface Level Communication

There are two packet structures are defined for communication: Short Packets (SPa) and Long Packets (LPa).

For both packet structures, the Data Identifier (DI) is always the first bit of the packet.

The Packet Footer for Long Packets is a checksum value which is calculated from the Data Payload in the Long Packet. The checksum is using a 16-bit Cyclic Redundancy Check(CRC) with a generator polynomial of $x^{16} + x^{12} + x^5 + x^0$. The Receiver will calculate checksum value from received Data Payload and compare this CRC value with the Packet Footer sent by transmitter. If calculated CRC values equal to Packet Footer, the received Data Payload are correct. The CRC implementation is presented as the following.



5.4.2.8 Packet Footer for Long Packets

There are several common elements for Long and Short Packets such as DI byte and ECC byte. The DI byte consists of 2-bit Virtual Channel identifier (VC = DI[7:6]) and 6-bit Data Type field (DT = DI[5:0]). The DI structure is as the following:

Data Identifier(DI)							
Virtual Channel(VC)		Data Type(DT)					
Bit-7	Bit-6	Bit-5	Bit-4	Bit-3	Bit-2	Bit-1	Bit-0

Virtual Channel is used to assign which peripherals for packets transmission. Data Type specifies if the packet is a Long or Short Packet and the packet format. The Data Type are defined as the table below:

Data Type(hex)	Data Type(binary)	Description	Packet Size
0x02	00 0010	Acknowledge and Error Report	Short
0x11	01 0001	Generic Short READ Response, 1 byte returned	Short
0x12	01 0010	Generic Short READ Response, 2 bytes returned	Short
0x1A	01 1010	Generic Long READ Response	Long
0x1C	01 1100	DCS Long READ Response	Long
0x21	10 0001	DCS Short READ Response, 1 byte returned	Short
0x22	10 0010	DCS Short READ Response, 2 bytes returned	Short

Data Types for Processor-Sourced Packets

Data Type(hex)	Data Type(binary)	Description	Packet Size
0x01	00 0001	Sync Event, V Sync Start	Short
0x11	01 0001	Sync Event, V Sync End	Short
0x21	10 0001	Sync Event, H Sync Start	Short
0x31	11 0001	Sync Event, H Sync End	Short
0x07	00 0111	Compression Mode Command	Short
0x08	00 1000	End of Transmission packet (EoTp)	Short
0x03	00 0011	Generic Short WRITE, no parameters	Short
0x13	01 0011	Generic Short WRITE, 1 parameter	Short
0x23	10 0011	Generic Short WRITE, 2 parameters	Short
0x04	00 0100	Generic READ, no parameters	Short
0x14	01 0100	Generic READ, 1 parameter	Short
0x24	10 0100	Generic READ, 2 parameters	Short
0x05	00 0101	DCS Short WRITE, no parameters	Short
0x15	01 0101	DCS Short WRITE, 1 parameter	Short
0x06	00 0110	DCS READ, no parameters	Short
0x37	11 0111	Set Maximum Return Packet Size	Short
0x09	00 1001	Null Packet, no data	Long
0x19	01 1001	Blanking Packet, no data	Long
0x29	10 1001	Generic Long Write	Long
0x39	11 1001	DCS Long Write	Long
0x0A	00 1010	Picture Parameter Set	Long
0x0B	00 1011	Compressed Pixel Stream	Long
0x0E	00 1110	Packed Pixel Stream, 16-bit RGB, 5-6-5 Format	Long

0x1E	01 1110	Packed Pixel Stream, 18-bit RGB, 6-6-6 Format	Long
0x2E	10 1110	Loosely Packed Pixel Stream, 18-bit RGB, 6-6-6 Format	Long
0x3E	11 1110	Packed Pixel Stream, 24-bit RGB, 8-8-8 Format	Long

5.4.2.9 Packet Pixel Stream Format

There are 4 packet pixel stream format: 16-bit RGB 5-6-5, 18-bit RGB 6-6-6, loosely packed 18-bit RGB 6-6-6 and 24-bit RGB 8-8-8. The Data Type for these pixel stream format are shown as the table below.

Data Type(hex)	Data Type(binary)	Description	Packet Size
0x0E	00 1110	Packed Pixel Stream, 16-bit RGB, 5-6-5 Format	Long
0x1E	01 1110	Packed Pixel Stream, 18-bit RGB, 6-6-6 Format	Long
0x2E	10 1110	Loosely Packed Pixel Stream, 18-bit RGB, 6-6-6 Format	Long
0x3E	11 1110	Packed Pixel Stream, 24-bit RGB, 8-8-8 Format	Long

Note: 0.39" Micro OLED only support 24 bit RGB pixel stream format

6. Absolute Maximum Ratings

The absolute maximum rating is listed on the below table. When the Driver IC of 0.39" is used beyond the absolute maximum ratings, it may be permanently damaged. It is strongly recommended use the driver IC within the following specified limits for normal operation. If these electrical characteristic conditions are exceeded during normal operation, the driver IC will malfunction and cause poor reliability.

Item	Symbol	Value	Unit
Power Supply Voltage	VDDI	4	V
	AVDD-AVSS	7	V
	AVEE-AVSS	7	V
MIPI Differential Input	CLKP_PTA/B, CLKN_PTA/B DATAP0_PTA/B, DATAN0_PTA/B DATAP1_PTA/B, DATAN1_PTA/B DATAP2_PTA/B, DATAN2_PTA/B DATAP3_PTA/B, DATAN3_PTA/B	1.32	V
Environment temperature	Topr	-20 ~ 60	°C
Storage temperature	Tstg	-20 ~ 70	°C

Note:

1. The environment temperature is not a RA test temperature.

7. Electrical Characteristics

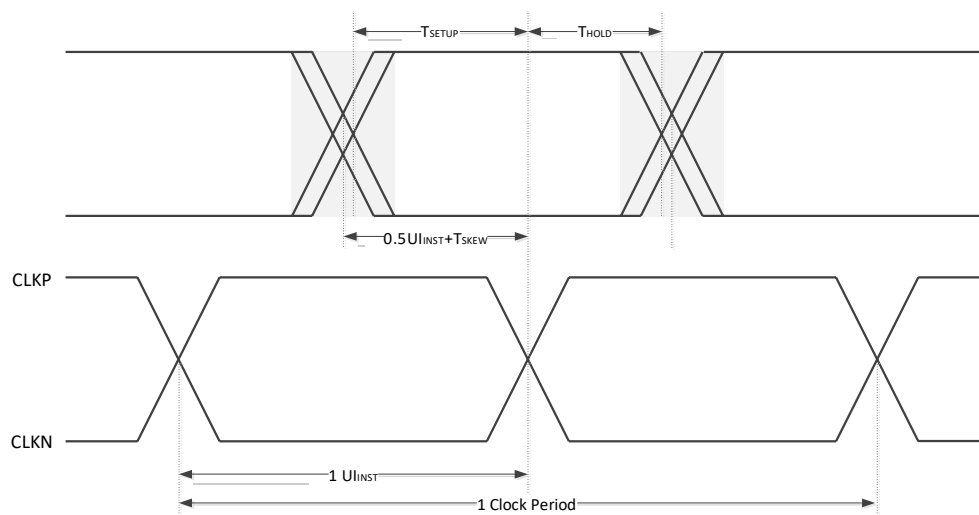
7.1 DC Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Power & Operation Voltage/Current For FPC Module						
AVDD Input Level	AVDD Voltage	-	5.0	5.4	6.	V
	AVDD Input Current	-	25	-	-	mA
AVEE Input Level	AVEE Voltage	-	-6.0	-5.4	-5.0	V
	AVEE Input Current	-	18	-	-	mA
VDDI Input Level	VDDI Voltage	-	1.65	1.8	1.95	V
	VDDI Input Current	-	41	-	-	mA
MIPI I/O Power Supply	MVDD	-	-	1.2	-	V

7.2 AC Characteristics

7.2.1 MIPI High Speed Mode Characteristics

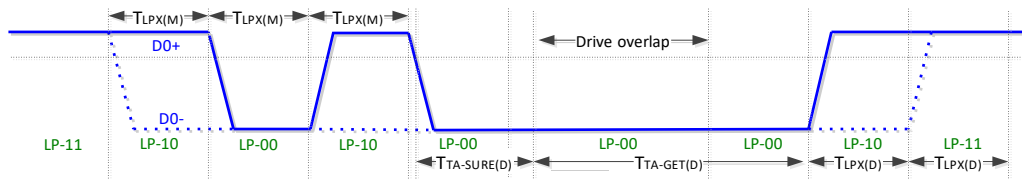
Parameter	Symbol	Min	Typ.	Max	Unit
UI instantaneous	UIINST	1	-	3	ns
T Data to Clock Skew	TSKEW	-0.15	-	0.15	UIHS
RX Data to Clock Setup Time Tolerance	TSETUP	0.15	-	-	UIHS
RX Data to Clock Hold Time Tolerance	THOLD	0.15	-	-	UIHS



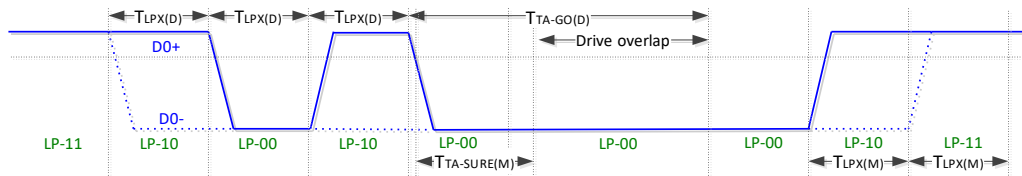
7.2.2 MIPI Low Power Mode Characteristics

Parameter	Description	Min.	Typ.	Max.	Unit
TLPX(M)	Transmitted length of any Low-Power state period (MCU to display module)	50	-	-	ns
TLPX(D)	Transmitted length of any Low-Power state period (display module to MCU)	50	-	-	ns
TTA-SURE	Time that the new transmitter waits after the LP-10 state before transmitting the Bridge state(LP-00) during a Link Turnaround	TLPX	-	2*TLPX	
TTA-GET	Time that the new transmitter drives the Bridge state(LP-00) after accepting control during a Link Turnaround	5*TLPX			
TTA-GO	Time that the transmitter drives the Bridge state(LP-00) before releasing control during a Link Turnaround	4*TLPX			

- Bus Turnaround from MPU to display module



- Bus Turnaround from display module to MPU



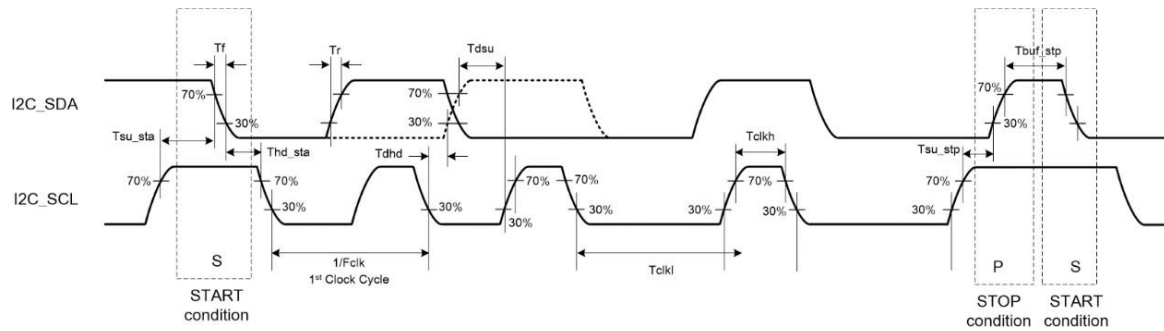
7.2.3 MIPI Video Timing Specification.

1920×1080@90Hz					
H	Hsync	32	V	Vsync	4
	HBP	72		VBP	8
	Hactive	1920		Vactive	1080
	HFP	56		VFP	8
Pclk （MHz）	969.41				
1920×1080@60Hz					
H	Hsync	32	V	Vsync	4
	HBP	72		VBP	8
	Hactive	1920		Vactive	1080
	HFP	56		VFP	8
Pclk （MHz）	1064.45				
Recommended configuration of MIPI					
D-PHY V1.2DSI 1.01	CLK Mode: Discontinue Mode				
	MIPI Lane: 4 Lanes@60Hz. 8 Lanes@90Hz				
	Video Mode: Burst Mode				
	HS Speed: 300Mbps ~ 1.0Gbps per Lane				
	LP Speed: 10Mbps （max）				
	General Packet Structure: DCS Mode .Data Type of Packet: 0x39 or 0x05 or 0x15				

※ This parameter is a typical example illustrating the display timing. XINSUN cannot assume responsibility for any problems arising out of the use of the circuit.

7.2.4 I2C Interface Timing

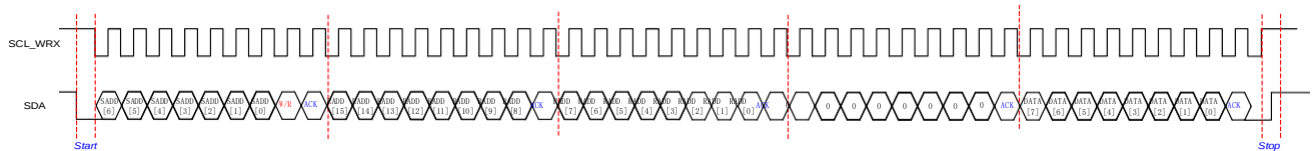
Parameter	Symbol	Min.	Typ.	Max.	Unit
I2C Clock Frequency	Fclk	-	-	400	kHz
I2C Clock Low	Tckl	1300	-	-	ns
I2C Clock High	Tckh	600	-	-	ns
I2C Data Rising Time	Tdr	-	-	300	ns
I2C Data Falling Time	Tdf	-	-	300	ns
I2C Data Setup Time	Tdsu	100	-	-	ns
I2C Data Hold Time	Tdhd	-	-	TBD	ns
I2C Setup Time (Start Condition)	Tsu_sta	600	-	-	ns
I2C Hold Time (Start Condition)	Thd_sta	600	-	-	ns
I2C Setup Time (Stop Condition)	Tsu_stp	600	-	-	ns
I2C Bus Free Time (Stop Condition)	Tbuf_stp	1300	-	-	ns



Notes:

No.	ITEM	Description	Note
1	Slave address	0x4C	
2	Pull-up resistor	4.7KΩ@100Kbps	
3	Read bit	Setting "1" for write	
4	Write bit	Setting "0" for write	
5	Start condition	SDA is setting from "1" to "0" when SCL is "1"	
6	Stop condition	SDA is setting from "0" to "1" when SCL is "1"	

7.2.5 I2C Interface Waveform



SADD[6:0]—Slave address.

W—Write bit. R—Read bit. W=0. R=1.

ACK—Acknowledge bit. ACK=0.

RADD[15:0]—Register address. RADD[7:0] is for shifting.

DATA[7:0]—The parameter of register.

Code Example:

MIPI format: regw 0x51 0xFF 0x01

IIC format: regw 0x51 0x00 0x00 0xFF

regw 0x51 0x01 0x00 0x01

7.3 Power Consumption

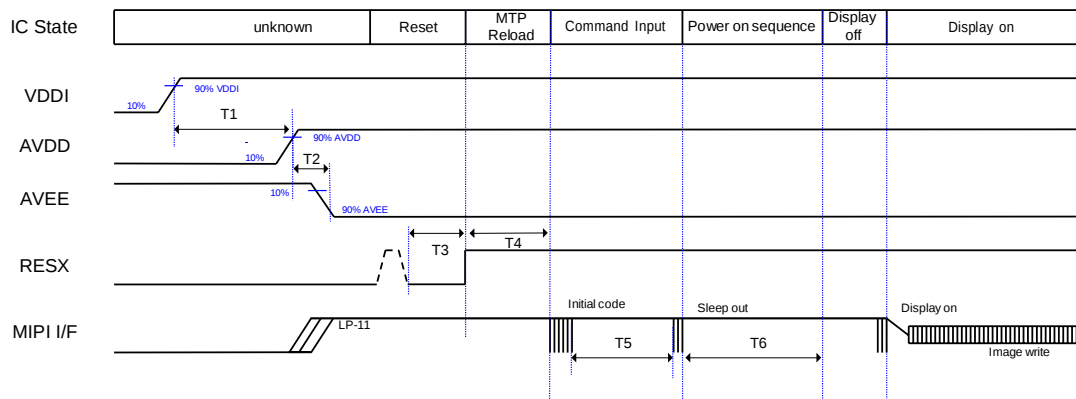
Item		Symbol	Typ.	Unit
			1000cd/m ²	
FPC module	Total	Total power	310	mW

Note: All white raster display, clock frequency=148.5MHz, frame rate=60Hz. White.

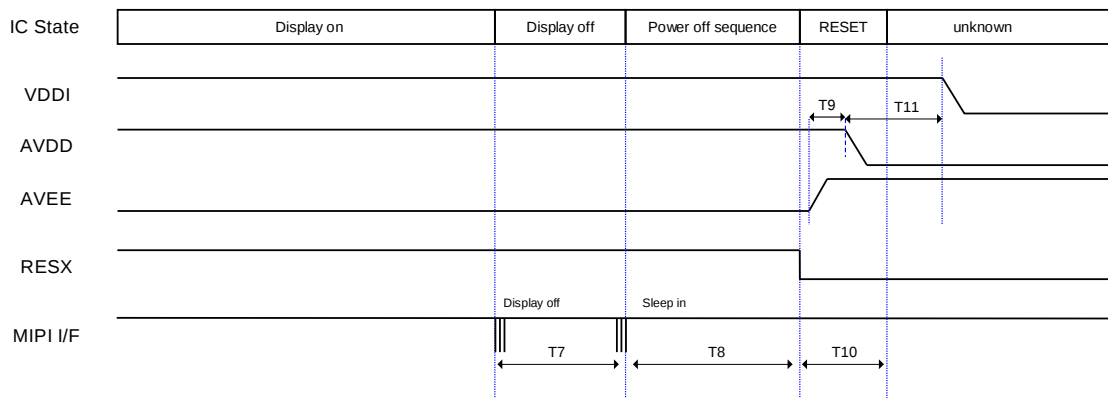
8. Power Supply Sequence

8.1 Power On/Off Sequence

Power on sequence For FPC Module



Power off sequence For FPC Module



9. Description of Function

9.1 Display Mode

9.1.1 Power Mode

ITEM	Code value
Sleep In	0x10
Sleep Out	0x11
Display On	0x29
Display Off	0x28

9.1.2 Idle Mode

ITEM	Code value
Idle On	0x39(Default value)
Idle Off	0x38

9.1.3 BIST Mode

Register setting :

◆ BIST On/Off Control (C4h)

Instruction	R/W	Address name		Parameter								
		MIPI	Other	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0
BISTONOFF	R/W	C4h	C400h	-	1	0	1	0	0	1	0	1
			C401h	-	0	1	0	1	0	1	0	1
			C402h	-	-	-	-	-	-	-	-	BION1
			C403h	-	BION2	-	-	-	-	-	-	-
Description	This command is used to control BIST function (Free Run mode). BIST function enable step: Enter Sleep-In(10h) mode. Setting PATENICYC[1:0] and BISTPATEN[11:0] to control the display cycle time and pattern. Setting BION1="1" and BION2="1", the driver IC will start to run the BIST function. BIST function disable step: Setting BION1="0" and BION2="0",the driver IC will return to normal function. Sending MIPI video data and enter Sleep-Out(11h) mode for normal display.											
Restriction	-											

Default		Status	Default Value	
		Power On Sequence	C400h	AAh
			C401h	55h
			C402h	00h
			C403h	00h

◆ BIST CTRL (C5h)

Instruction	R/W	Address name		Parameter								
		MIPI	I2C	D15-18	D7	D6	D5	D4	D3	D2	D1	D0
BISTEST	R/W	C5h	C500h	-	0	0	PATENICYC[1:0]		BISTPATEN[11:8]			
			C501h	-	BISTPATEN[7:0]							
			C502h	-	GRAY_LEVEL[7:0]							
Description	This command is used to set the display pattern in BIST function. PATENICYC[1:0] : Cycle time between each display pattern.											
	PATENICYC[1:0]						Pattern cycle time					
	0h						256 Frame					
	1h						512 Frame					
	2h						1024 Frame					
	3h						2048 Frame					
	BISTPATEN[11:0] : Select the display pattern in BIST function.											
	BISTPATEN[9:0]						Description					
	BISTPATEN[0]						Red pattern.					
	BISTPATEN[1]						Green pattern.					
	BISTPATEN[2]						Blue pattern.					
	BISTPATEN[3]						Black pattern.					
	BISTPATEN[4]						Gray Level pattern. (Set by BIST_GRAY_LEVEL[7:0])					
	BISTPATEN[5]						Vertical Gradation pattern.					
	BISTPATEN[6]						Horizontal Gradation pattern.					
	BISTPATEN[7]						Color Bar pattern.					
	BISTPATEN[8]						Crosstalk with boundary pattern.					
	BISTPATEN[9]						Source CP Pattern					
	BISTPATEN[10]						Gamma CP Pattern					
	BISTPATEN[11]						Reserved					
	Notel: the patterns which the bit number of BISTPATEN[9:0] is set to “1” will display and change automatically.											
	Note2: When BISTPATEN[11:0]=12’h000, display pattern will be black pattern.											
	GRAY_LEVEL[7:0] : Set the gray level when BISTPATEN[4]=”1” in BIST function.											
	GRAY_LEVEL[7:0]						Description					

	0h	Gray Level : 00h
	1h	Gray Level : 01h
	2h	Gray Level : 02h
	:	:
	FDh	Gray Level : FDh
	FEh	Gray Level : FEh
	FFh	Gray Level : FFh
Restriction	-	
Default	Status	Default Value
	Power On Sequence	C500h 01h
		C501h FFh
		C502h FFh

9.1.4 Command Enable Mode

F000H	MAUCCTR											
		Address		Parameter								
Instruction	R/W	MIPI	Other	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0
MAUCCTR	W	10h	F000h	-	1	0	1	0	1	0	1	0
			F001h	-	-	-	-	EN_C MD2	PAGE[3:0]			
Description	This command is used to enable the access of CMD2 page											
	Bit			Symbol			Description			Comment		
	D4			EN_CMD2			Enable access of CMD2 page			1= enable 0= disable		
	D[3:0]			PAGE[3:0]			CMD2 Page selection			0=CMD2 Page0 1=CMD2 Page1 2=CMD2 Page2 3=CMD2 Page3 4=CMD2 Page4 Others=Reserved		
Restriction	-											
Default	Status				Default Value							
	Power On Sequence				F000h				Aah			
					F001h				00h			

◆ DISPCTL (B8h): Display Control



Instruction	R/W	Address		Parameter								
DISPCTL	R/W	MIPI	Other	D15-18	D7	D6	D5	D4	D3	D2	D1	D0
BISTEST	R/W	B8h	B800h	-	-	-	-	-	-	CTB	CRL	1
Description	CTB: Horizontal Flip.											
	CTB					Scan Direction						
	0h					Normal Display						
	1h					Vertical Flip						
	Note: The display corresponds to the result of CTB^ RSMY (CMD1, 36h)											
	CRL: Vertical Flip.											
	CRL					Scan Direction						
	0h					Normal Display						
	1h					Horizontal Flip						
	Note: The display corresponds to the result of CRL ^ RSMX (CMD1, 36h).											
Restriction	-											
Default	Status			Default Value								
	Power On Sequence			B800h					01h			

9.2 Brightness Control (BC) Functions

This function adjusts the gamma parameter according to the register 51h and 53h setting to adjust the luminance.

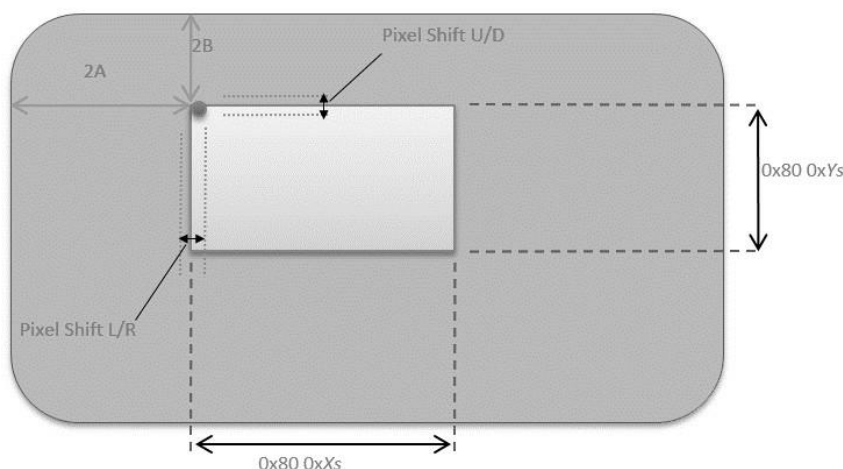
◆ Register setting

BCCTR3 (C2h):

C2H	WRCTRLD												
Instruction	R/W	Address		Parameter									
		MIPI	I2C	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0	
BCCTR3	R/W	C2	C200h	-	EM_WD_0[7:0]								
			C201h		EM_WD_1[7:0]								
			C202h		EM_WD_2[7:0]								
			C203h		0	0	0	0	0	0	0	0	
			C204h		EM_WD_IDLE[7:0]								
Description	EM-WD-x [7:0]: Duty ratio of Emission for DBV_P00~P03.												
	EM_WD_0[7:0]EM_WD_1[7:0] EM_WD_2[7:0]				Duty ratio of Emission for DBV_P00~P03								
	0h				1/256								
	1h				2/256								
	.				.								
	FEh				255/256								
	FFh				256/256								
	EM_WD_IDLE [7:0]: Duty ratio of Emission in Idle mode.												
	EM_WD_IDLE[7:0]				Width of EM_STV01 in Idle mode								
	0h				1/256								
	1h				2/256								
	.				.								
	FEh				255/256								
	FFh				256/256								
Restriction													
Default	Status		Default Value										
	Power On Sequence		C200h						00h				
			C201h						00h				
			C202h						00h				
			C203h						00h				
			C204h						00h				

9.3 Display Active-Area(AA) Control

ITEM	Description	Code Value
Resolution	X-direction: Support 8N, N=40~240 Y-direction: support 8M, M=30~135	CMD1: 0x80(NC[7:0] NL[7:0])
Active-Area(AA)control	Display start pointer	Xs: CMD1: 0x2A Ys: CMD1: 0x2B
	Pixel shift: $\pm 12\text{pixel/step}=4\text{pixel}$	CMD2 Page0: 0xB4

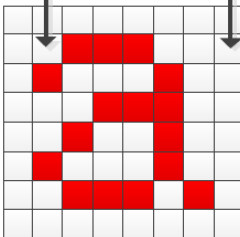


9.3.1 Resolution (80h CMD1)

8000H		RESCTRL1											
Instruction	R/W	Address		Parameter									
		MIPI	Other	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0	
RESCTR L 1	R/W	80h	8000h	-	-	-	-	-	-	-	-	OSC_FREQ_SEL	
			8001h	-	NC[7:0]								
			8002h	-	NL[7:0]								
Description	This command is used to set panel type and display resolution.												
	Bit	Symbol		Description				Comment					
	D0	OSC_FREQ_SEL		OSC frequency selection				1= 80MHz 0= 60MHz					
	D[7:0]	NC[7:0]		X-axis resolution				X-axis resolution= NC[7:0]*8					
	D[7:0]	NL[7:0]		Y-axis resolution				Y-axis resolution= NL[7:0]*8					
Restriction	Resolution switch is only valid in <i>SLPIN</i> mode.												

Default	Status		Default Value	
	Power On Sequence		8000h	01h
			8001h	F0h
			8002h	87h

9.3.2 Active-Area (AA) control Column Address Set (2Ah CMD1)

2A00H			WRCTRLD										
Instruction	R/W	Address		Parameter									
		MIPI	I2C	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0	
RESCTRL 1	W	2Ah	2A00h	-	XS[15:8]								
			2A01h		XS[7:0]								
Description	This command indicates display start position of display module in columns. XS[15:0]: Display line start position XE[15:0]: Display line end position] XS[15:0] XE[15:0] 												
Restriction	XS[15:0] must be equal to or less than XE[15:0].When XS[15:0] or XE[15:0] is greater than maximum like below, data of out of range will be ignored. For example: NC="10Eh"; NL="1E0h" (Resolution=1080x1920)Parameter range= 0 ≤ XS[15:0] ≤ XE[15:0] ≤ 1919 (77Fh) When display module is on distribute driving mode, XS and XE should follow the rule as below: XS= 0 + 4N, N=integer XE= 3 + 4N, N=integer												
Default	Status		Default Value										
	Power On Sequence		2A00h				00h						
			2A01h				00h						
			2A02h				07h						
			2A03h				7Fh						

9.3.3 Active-Area (AA) control Row Address Set (2Bh CMD1)

2B00H		WRCTRLD										
Instruction	R/W	Address		Parameter								
		MIPI	I2C	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0
RESCTRL 1	W	2Bh	2B00h	-	YS[15:8]							
			2B01h		YS[7:0]							
			2B02h		YE[15:8]							

		2B03h		YE[7:0]												
Description	This command indicates display start position of display module in rows. YS[15:0]: Display line start position YE[15:0]: Display line end position															
Restriction	YS[15:0] must be equal to or less than YE[15:0].When YS[15:0] or YE[15:0] is greater than maximum like below, data of out of range will be ignored. For example: NC="10Eh"; NL="1E0h" (Resolution=1080x1920) Parameter range= $0 \leq YS[15:0] \leq YE[15:0] \leq 1079$ (437h) When display module is on distribute driving mode, YS and YE should follow the rule as below: YS= $0 + 4N$, N=integer YE= $3 + 4N$, N=integer															
Default	<table><tr><th>Status</th><th colspan="2">Default Value</th></tr><tr><td rowspan="4">Power On Sequence</td><td>2B00h</td><td>00h</td></tr><tr><td>2B01h</td><td>00h</td></tr><tr><td>2B02h</td><td>04h</td></tr><tr><td>2B03h</td><td>37h</td></tr></table>				Status	Default Value		Power On Sequence	2B00h	00h	2B01h	00h	2B02h	04h	2B03h	37h
Status	Default Value															
Power On Sequence	2B00h	00h														
	2B01h	00h														
	2B02h	04h														
	2B03h	37h														

9.3.4 Active-Area (AA) control Pixel shift s Set (B4h CMD1)

Instruction	R/W	Address		Parameter								
		MIPI	Other	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0
PXLSHIFTCTR	R/W	B4h	B400h	-	PIXEL_SHIFT_X_DIR	-		PIXEL_SHIFT_X_COUNT[4:0]				
			B401h	-	PIXEL_SHIFT_Y_DIR	-		PIXEL_SHIFT_Y_COUNT[4:0]				

Description	PIXEL_SHIFT_X_DIR: Pixel shift direction of X-axis															
	PIXEL_SHIFT_X_DIR		Pixel Shift Direction of X-axis													
	00h		Left													
	01h		Right													
	PIXEL_SHIFT_X_COUNT[4:0]: Pixel shift of X-axis															
	PIXEL_SHIFT_X_COUNT[4:0]		Pixel Shift of X-axis													
	00h		0-pixels													
	01h		1-pixels													
	02h		2-pixels													
	0Eh		14-pixels													
	0Fh		15-pixels													
	10h		16-pixels													
	Others		Reserved													
	PIXEL_SHIFT_Y_DIR: Pixel shift direction of Y-axis															
	PIXEL_SHIFT_Y_DIR		Pixel Shift Direction of Y-axis													
	00h		Up													
	01h		Down													
	PIXEL_SHIFT_Y_COUNT[4:0]: Pixel shift of Y-axis															
	PIXEL_SHIFT_Y_COUNT[4:0]		Pixel Shift of Y-axis													
	00h		0-pixels													
	01h		1-pixels													
	02h		2-pixels													
	0Eh		14-pixels													
	0Fh		15-pixels													
	10h		16-pixels													
	Others		Reserved													
	<table><tr><th>Bit</th><th>Symbol</th><th>Description</th><th>Comment</th></tr><tr><td>D1</td><td>RSMX</td><td>Horizontal Flip</td><td>1=Normal Display 0=Horizontal Flip</td></tr><tr><td>D0</td><td>RSMY</td><td>Vertical Flip</td><td>1= Normal Display 0= Vertical Flip</td></tr></table>				Bit	Symbol	Description	Comment	D1	RSMX	Horizontal Flip	1=Normal Display 0=Horizontal Flip	D0	RSMY	Vertical Flip	1= Normal Display 0= Vertical Flip
	Bit	Symbol	Description	Comment												
	D1	RSMX	Horizontal Flip	1=Normal Display 0=Horizontal Flip												
D0	RSMY	Vertical Flip	1= Normal Display 0= Vertical Flip													

Code Example :

mipi.write 0x39 0xB4 0x00 0x00 0x18 0x18 (0x18 : Pixel offset value 24 in X/Y direction)

9.4 Scan direction selection (36h CMD1)

3600H	WRCTRLD																																			
Instruction	R/W	Address		Parameter																																
		MIPI	I2C	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0																								
WRCTRLD	W	36h	3600h	-	-	-	-	-	-	-	RSM X	RSM Y																								
Description	This command set scan direction of source and gate and data order.																																			
	Input Image → <table><tr><td>RSMX</td><td>RSMY</td><td>Display</td></tr><tr><td>0</td><td>0</td><td></td></tr><tr><td>0</td><td>1</td><td></td></tr><tr><td>1</td><td>0</td><td></td></tr><tr><td>1</td><td>1</td><td></td></tr></table> Input Data Order → <table><tr><td>RGB</td><td>Panel Display Color Order</td></tr><tr><td>0</td><td></td></tr><tr><td>1</td><td></td></tr></table>												RSMX	RSMY	Display	0	0		0	1		1	0		1	1		RGB	Panel Display Color Order	0		1				
RSMX	RSMY	Display																																		
0	0																																			
0	1																																			
1	0																																			
1	1																																			
RGB	Panel Display Color Order																																			
0																																				
1																																				
Restriction	-																																			
Default	<table><tr><td>Status</td><td colspan="11">Default Value</td></tr><tr><td>Power On Sequence</td><td colspan="9">5300h</td><td colspan="2">00h</td></tr></table>												Status	Default Value											Power On Sequence	5300h									00h	
	Status	Default Value																																		
Power On Sequence	5300h									00h																										

9.5 Read module display status

9.5.1 Read Display Power Mode (0Ah CMD1)

0A00H		WRCTRLD										
Instruction	R/W	Address		Parameter								
		MIPI	I2C	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0
WRCTRLD	R	0Ah	0A00h	-	D7	D6	-	D4	D3	D2	-	-
Description	This command indicates the status of display driver’s power and operation mode:											
	Bit	Symbol		Description				Comment				
	D7	BSTON		Boost Status				1=Boost On 0=Boost Off				
	D6	IDMON		Idle Mode On/Off				1=Idle Mode On 0=Idle mode Off				
	D4	SLPON		Sleep In/Out				1=Sleep Out 0=Sleep In				
	D3	NOR		Display Normal Mode On/Off				1= Display Normal On 0= Display Normal Off				
	D2	DISPON		Display On/Off				1=Display On 0=Display Off				
Restriction	-											
Default												
	Status				Default Value							
	Power On Sequence				0A00h				08h			

9.5.2 MIPI Error Report (68h CMD1)

2B00H	WRCTRLD											
Instruction	R/W	Address		Parameter								
		MIPI	I2C	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0
MERR	R	68h	6800h	-	ERPA[15:8]							
			6801h		ERPA[7:0]							
			6802h		ERP[B[15:8]							
			6803h		ERP[B[7:0]							
Description	This command is used to read DSI errors of MIPI port A											
	Symbol		Description									
	ERPA[15]		DSI Protocol Violation									
	ERPA[14]		Reserved									
	ERPA[13]		Invalid Transmission Length									
	ERPA[12]		DSI VC ID Invalid									
	ERPA[11]		DSI Data Type Not Recognized									
	ERPA[10]		Payload Checksum Error(Long packet only)									
	ERPA[9]		ECC Error, multi-bit (detected, not corrected)									
	ERPA[8]		ECC Error, single-bit (detected, not corrected)									
	ERPA[7]		Contention Detected									
	ERPA[6]		False Control Error									
	ERPA[5]		Peripheral Timeout Error									
	ERPA[4]		Low-Power Transmit Sync Error									
	ERPA[3]		Escape Mode Entry Command Error									
	ERPA[2]		EoT Sync Error									
	ERPA[1]		SoT Sync Error									
	ERPA[0]		SoT Error									
Restriction												
Default												
	Status			Default Value								
	Power On Sequence			6800h					00h			
6801h					00h							

9.6 Auto Temperature Compensation Function

Brightness and white point of OLED depends on display panel temperature as show in below. This module integrates Brightness and white point compensation function against panel temperature variation. This function allows to sustain relatively constant luminance and white point even if panel temperature changing as shown in below.

◆ Register Settings

2300H	ALLPON											
Instruction	R/W	Address name		Parameter								
		MIPI	Other	D15-D8	D7	D6	D5	D4	D3	D2	D1	D0
ALLPON	R/W	25h	2500h	-	-	-	-	-	-	-	-	TC_ENABLE
Description	This command is used to turn on temperature sensor.											
Restriction	-											
Default	Status		Default Value									
	Power On Sequence		2500h					00h				

10. Optical Characteristics

10.1 Optical Characteristics

Item		Specification..	
White Brightness (255 Level)	L	300±20% cd/m 2	
White Uniformity 9 Point	White (255 Level)	>80%	
View Angle(White)	Lum.Decay(50%)	-30°~30°	
	Color Shift($\Delta u'v' < 0.025$)	-10°~10°	
Contrast	CR	>5000:1	
Color Coordinate	Red	CIE-x	0.63±0.05
		CIE-y	0.34±0.05
	Green	CIE-x	0.27±0.05
		CIE-y	0.63±0.05
	Blue	CIE-x	0.15±0.05
		CIE-y	0.09±0.05
	White	CIE-x	0.31±0.05
		CIE-y	0.33±0.05
Color Gamut(NTSC)		>60%	
Color Temperature		>5000K	

Notes:

The brightness of the product will be measured after 5 minutes of stabilization for the white screen at room temperature.

The formula of the brightness uniformity at 9 points of the white screen is $\text{Uniformity} = 1 - (\text{Max.} - \text{Min.}) / (\text{Ave.})$, and the Max., Min. and Ave. represent the maximum, minimum and average of the brightness of 9 points, respectively.

10.2 Measurement System Measurement Method

The luminance and chromaticity are measured in Measurement System A shown below:

Measurement temperature: $T_{pnl} = 40^{\circ}\text{C}$

Measurement point: One point on the screen center

All white display: All RGB signal data is set to High.

All black display: All RGB signal data is set to Low.

Luminance and chromaticity: Measure the luminance and chromaticity in all white display in Measurement System A.

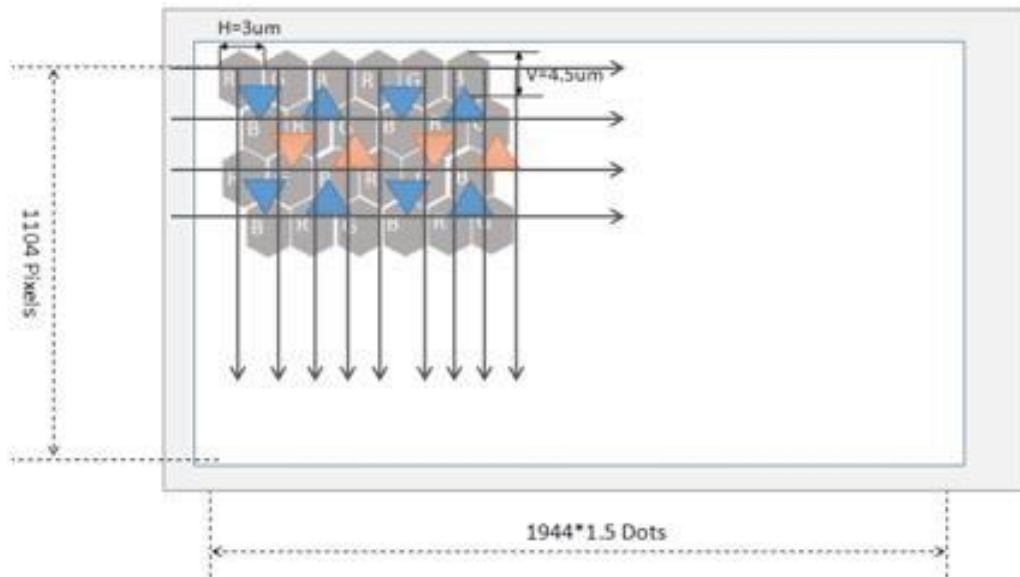
Contrast: Measure the luminance in all white display (@ : 300cd/m^2) and all black display in Measurement System A, and substitute them into the formula below.

Contrast = Luminance in all white display / Luminance in all black display

10.3 Reliability test

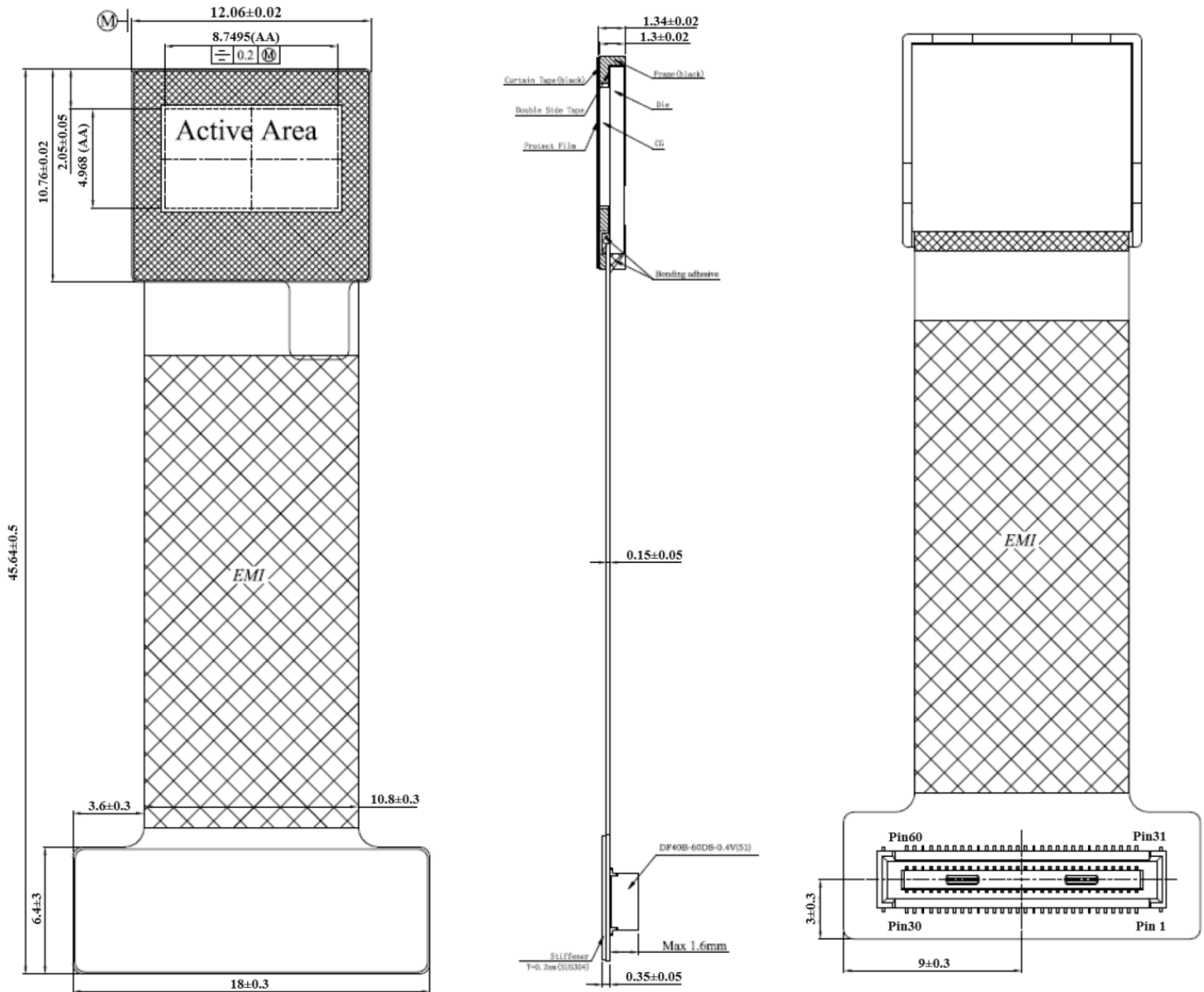
Item	Test conditions	Specification	Test frequency
HTS (High Temperature Storage)	Keep 70°C for 24hrs	The module can be lit up normally after reaching 20°C.	5pcs/lot
LTS (Low temperature Storage)	Keep -20°C for 24hrs	The module can be lit up normally after reaching 20°C.	5pcs/lot
HTO (High Temperature Operation)	Keep 60°C for 2hrs; Rate of temperature change: 3°C/min;	The module can be lit up normally at 60°C.	5pcs/lot
LTO (Low Temperature Operation)	Keep -20°C for 2hrs; Rate of temperature change: 3°C/min	The module can be lit up normally at -20°C.	5pcs/lot
VIB (Vibration)	Vibration frequency : 5HZ~200HZ~5HZ; Vibration direction : X/Y/Z; Peak acceleration : 1.5g; Vibration time: 6min/axis	The module can be lit up normally after experiment.	5pcs/lot
Shock	Peak acceleration : 50g, Pulse time : 11ms, Shock direction : X/Y/Z, Shock time: Twice/axis	The module can be lit up normally after experiment.	5pcs/lot
TST (Temperature Shock Test)	Temperature cycle interval : -20°C~70°C; Soaking time : 0.5hr; Temperature conversion time: ≤5mins; Shock times: 10 Cycles	The module can be lit up normally after reaching 20°C.	5pcs/lot
8585	Keep 85°C and humidity of 85% for 24hrs	The module can be lit up normally after reaching 20°C.	5pcs/lot

11. Pixel Alignment



※Including orbit margin

12. FPC Module Outline(Unit : mm)



Notes:

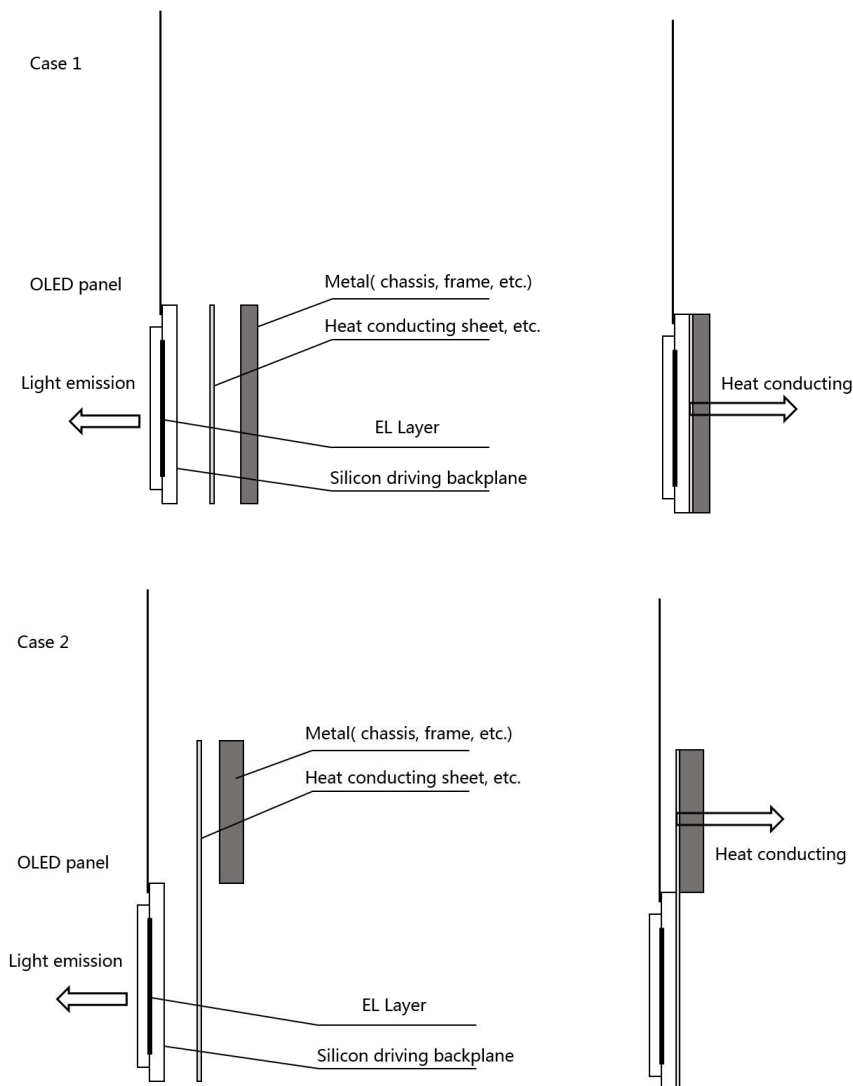
1. Display: 0.39 1920*1080 Micro OLED;
2. Connector: DF40B-60DS-0.4V (51) ;
3. General Tolerance: ± 0.1 ;
Unless Otherwise Specified Tolerance of Radius: ± 0.3
Module Bending Allowances SPEC: ± 0.3 ;
4. Conformity with ROHS.

13. Recommended Items

Suppression of the Panel Temperature

Temperature of organic EL panel tends to rise due to power consumption (heat generation) by the EL emission layer and the integrated silicon drive circuit. The temperature rise may cause luminance rise at initial state, or luminance drop by over time.

The temperature change in panel can be suppressed by establishing a thermal connection between panel rear surface (silicon substrate surface) and metal (chassis, frame, metal structure, etc.) at panel mount area, and the heat conducting sheet size can be changed, So highly recommend the heat conductive sheet between them as show in below. In order to ensure the normal operation of the screen, heat dissipation must be done to ensure that the screentemperature $< 60^{\circ}\text{C}$.



14. Notes on Handling

14.1 Static charge prevention

Be sure to take the following protective measures. Organic EL panels are easily damaged by static charges.

- (1) Use non-chargeable gloves or handle with bare hands.
- (2) Use a wrist strap connecting ground when handling.
- (3) Do not touch any electrodes on the panel.
- (4) Wear non-chargeable clothes and conductive shoes.
- (5) Install grounded conductive mats on the working floor and working table.
- (6) Keep the panel away from any charged materials.

14.2 Protection from dust and dirt

- (7) Operate in a clean environment.
- (8) Do not touch the panel surface. The surface is easily scratched.

When cleaning on panel surface, use a clean-room wiper with isopropyl alcohol. Be careful not to leave stains on the surface.

- (9) Use ionized air to blow dust off the panel surface.

14.3 Others

- (10) Not hold FPC (Flexible Printed Circuit) , not twist the FPC, not bend FPC because connection area between the FPC and panel is easily broken by mechanical stress.
- (11) The minimum fold radius of the FPC is 1.0 mm, So, do not fold the FPC less than 1.0mm radius.
- (12) Do not drop the module.
- (13) Do not twist or bend the module .
- (14) Keep the module away from heat sources.
- (15) Not be close the module to water or other solvents.
- (16) Do not store or use the module at high temperatures or high humidity circumstance, as the circumstance may affect module specifications.
- (17) When disposing of this, regard it as industrial waste and please comply with related regulations.
- (18) Do not store or use the panel in reactive chemical substance (including alcohol) environments, as these may affect the specifications.